

Amendments to the Specification

Please replace the paragraph beginning on page 4, line 1 with the following amended paragraph:

According to another aspect of the present invention, the transfer chamber is positioned below the reaction chamber, thereby making it possible to install a temporary storing mechanism for wafers adapted to increase the overall throughput of the semiconductor processing equipment. Additional details on the wafer buffer mechanism are provided in ~~Japanese Patent Application [provide identification for disclosure J-098JP], which is incorporated herein by reference.~~ U.S. Patent Application 10/187,670, filed 1 July 2002.

Please replace the paragraph beginning on page 5, line 28 with the following amended paragraph:

Furthermore, placing the transfer chamber 20 below the reaction chamber 30 provides multiple advantages. For example this configuration reduces the formation of film around the gate valve 14 that separates the transfer chamber 20 from the load lock chamber 10, thereby allowing deposition on multiple semiconductor wafers 40 without generating contaminating substances. Additionally, this configuration permits installation of a wafer buffer mechanism 42, that can be used in the transfer of semiconductor wafers 40 between the load lock chamber and the transfer chamber 20. Additional details of the wafer buffer mechanism 42 are available in ~~Japanese Patent Application [provide identification for disclosure J-098JP], which is incorporated herein by reference.~~ U.S. Patent Application 10/187,670, filed 1 July 2002.